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**Exotic Technologies Panel and  
Time Capsule Submission for  
Most Exciting Architecture at SC 20**

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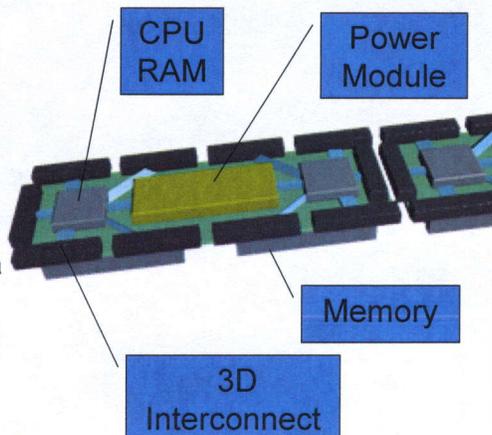
**SC 20 Supercomputer Projection**

	<b>Red Storm (Historical)</b>	<b>μP part only</b>	<b>My Entry</b>
<b>Total cores</b>	13,000×2	50,000×4	50,000×40
<b>Node Type</b>	μP	μP	μP & macro function
<b>Clock</b>	2.5 GHz	20 GHz	20 GHz
<b>Flops/chip</b>	5×2 GF	50×4 GF	1.6 TF
<b>Sys. Peak</b>	125 TF	80 PF	800 PF
<b>Maximum MPI Latency</b>	10 μS	100 ns	100 ns
<b>Power</b>	2 MW	2 MW	2 MW

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## Packaging for a Spatial Locality

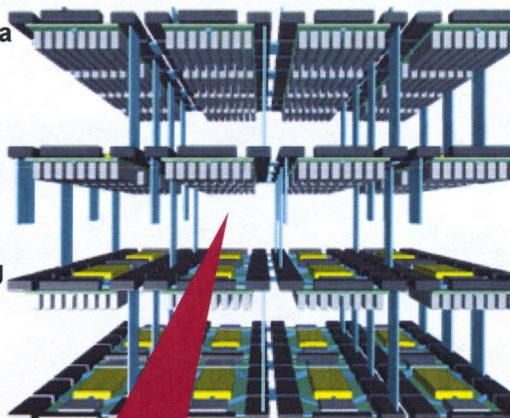
- **Basic Module**
  - 2 Chips
  - Each node 4 core conventional CPU plus
  - 36 accelerator cores
  - 1 GB+ on chip RAM
  - 100 GB memory on bottom of module
  - Each module includes a power unit
  - Six optical interconnect channels, 3D mesh



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## Packaging for a Spatial Locality

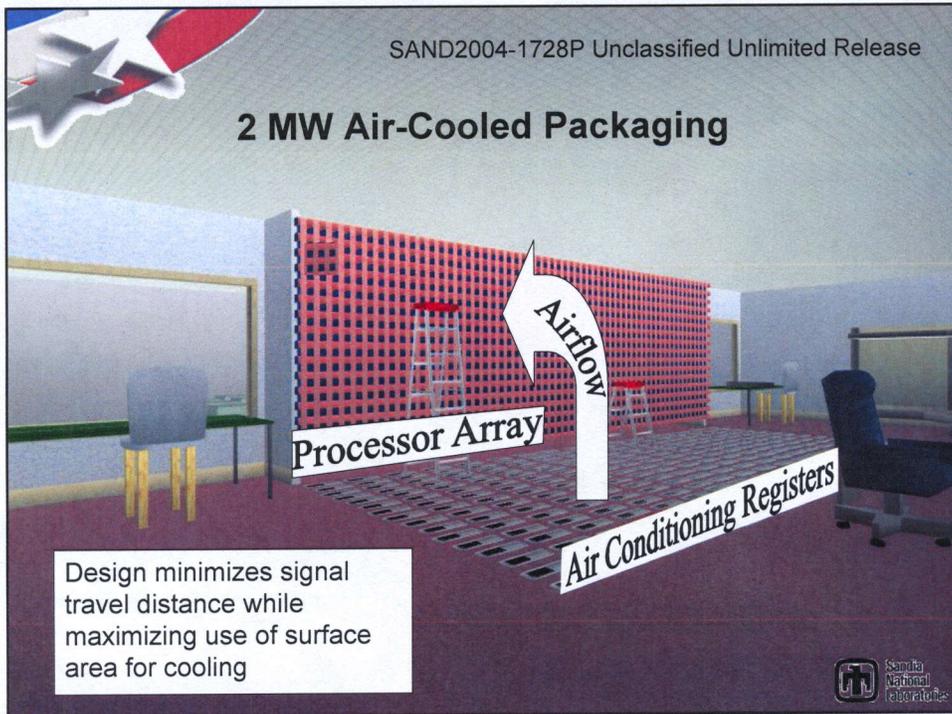
- Entire supercomputer is a single structure
- All mesh network connections are of constant length (8" max)
- Air flows front to back
  - General approach will work for liquid cooling as well



This region would be filled with heat sink

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## 2 MW Air-Cooled Packaging



Design minimizes signal travel distance while maximizing use of surface area for cooling

### Outline

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- Degree of Innovation
- Non-Architecture Projections
- Architecture Projections
- Programming
- Architecture Summary
- Current Activities to Watch and Why
- Conclusions

## Perspective on Innovation

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- $1992 + 14 = 2006$ ;  $2006 + 14 = 2020$
- If rate of innovation stays the same, we should see as big an advance to 2020 as we saw from “late nCUBE” through now
- However, I think SC is maturing. I think the community will only accept innovations backwards compatible with what we have now. If there is major innovation, I think it will be best represented in a new conference, say “I Robot 2020.”

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## Scaling Implications for CPUs

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- **5× performance increase for a single core**
  - Burger and Keckler study, slide follows
  - NOTE: Integrated RAM will increase this another 2×
- **64 cores of today's complexity**
  - 90 nm → 18 nm is 5×. Dual core × 5<sup>2</sup> → 50 ≈ 64
- I think we'll see a hybrid – to be discussed later

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## UT Austin Study (2000)

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- **The Study**
  - Clock Rate versus IPC:  
The End of the Road for  
Conventional  
Microarchitectures,  
Vikas Agarwal, M.S.  
Hrishikesh, Stephen W.  
Keckler, Doug Burger.  
27<sup>th</sup> Annual  
International  
Symposium on  
Computer Architecture
- **Conclusions (to be Explained)**
  - Modified ITRS roadmap predictions to be more friendly to architectures
  - Concluded there would be a 12%/year growth...
  - However, recent growth has been ~30%, with industry's maneuver to cheat the analysis instructive

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>18 - 20

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# Critical Evaluation Memory

For each Technology Entry (e.g. 1D Structures, sum horizontally over the 8 Criteria  
Max Sum = 24  
Min Sum = 8

Memory Device Technologies (Potential)	Scalability [A]	Performance [B]	Energy Efficiency [C]	OFF/ON "1"/"0" Ratio [D1]	Operational Reliability [E]	Operate Temp [F] ***	CMOS Technological Compatibility [G]**	CMOS Architectural Compatibility [H]*
Nano Floating Gate Memory	2.5	2.5	2.5	2.5	2.2	2.7	2.7	3.0
Engineered Tunnel Barrier Memory	2.2	2.3	2.3	2.3	2.4	2.8	2.8	3.0
Ferroelectric FET Memory	1.9	2.3	2.5	2.2	2.0	3.0	2.6	3.0
Insulator Resistance Change Memory	2.5	2.5	2.0	2.2	1.9	2.8	2.6	2.8
Polymer Memory	2.1	1.5	2.3	2.2	1.6	2.9	2.3	2.5
Molecular Memory	2.3	1.5	2.4	1.6	1.4	2.6	1.9	2.3

4 good options

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# Critical Evaluation Logic

For each Technology Entry (e.g. 1D Structures, sum horizontally over the 8 Criteria  
Max Sum = 24  
Min Sum = 8

Logic Device Technologies (Potential)	Scalability [A]	Performance [B]	Energy Efficiency [C]	Gain [D2]	Operational Reliability [E]	Room Temp Operation [F] ***	CMOS Technological Compatibility [G]**	CMOS Architectural Compatibility [H]*
1D Structures (CNTs & NWs)	2.4	2.5	2.3	2.3	2.1	2.3	2.3	2.8
Resonant Tunneling Devices	1.5	2.2	2.1	1.7	1.7	2.5	2.0	2.0
SETs	1.9	1.5	2.6	1.4	1.2	1.9	2.1	2.1
Molecular Devices	1.6	1.8	2.2	1.5	1.6	2.3	1.7	1.8
Ferromagnetic Devices	1.4	1.3	1.9	1.5	2.0	2.5	1.7	1.7
Spin Transistor	2.2	1.3	2.4	1.2	1.2	2.4	1.5	1.7

1 good option, and it is not a change for SC

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## Commodity $\mu$ P Architecture in 2020

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- Industry is now ramping the number of cores per die
- Intel and AMD are making serious noises about integrating graphics processors into CPU die
- I have special information that upcoming ITRS direction will advocate “macro functions” (to be explained later)
- These are self-confirming data points that answer the commodity  $\mu$ P architecture question
  - Note: this answer could be wrong...

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